


Date: 4/25/2021

Material Number: EFR32BG13P532F512GM48-C

Pkg Config.: PK1469

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Die Attach Epoxy	1.90	Copper	7440-50-8	10.000	0.190	100000	0.1406	1406
			Hardener (Proprietary)	Proprietary	2.000	0.038	20000	0.0281	281
			Liquid Rubber	Proprietary	12.500	0.238	125000	0.1757	1757
			Mixed Diluents	Proprietary	6.500	0.124	65000	0.0914	914
			Modified Epoxy Resins	Proprietary	1.500	0.028	15000	0.0211	211
			Silver	7440-22-4	67.500	1.282	675000	0.9488	9488
2	Bond Wire	0.35	Copper	7440-50-8	96.550	0.334	965500	0.2471	2471
			Gold	7440-57-5	0.350	0.001	3500	0.0009	9
			Palladium	7440-05-3	3.100	0.011	31000	0.0079	79
3	Plating - External	4.20	Tin	7440-31-5	100.000	4.200	1000000	3.1072	31072
4	Mold Compound	58.80	Carbon Black	1333-86-4	0.400	0.235	4000	0.1740	1740
			Epoxy Resin (Proprietary)	Proprietary	7.000	4.116	70000	3.0451	30451
			Metal Hydroxide	Proprietary	2.000	1.176	20000	0.8700	8700
			Phenol Resin (Proprietary)	Proprietary	5.000	2.940	50000	2.1750	21750
			Silica (Amorphous) B	60676-86-0	85.600	50.333	856000	37.2367	372367
5	Leadframe	65.30	Chromium	7440-47-3	0.250	0.163	2500	0.1208	1208
			Copper	7440-50-8	99.280	64.830	992800	47.9617	479617
			Tin	7440-31-5	0.250	0.163	2500	0.1208	1208
			Zinc	7440-66-6	0.220	0.144	2200	0.1063	1063
6	Plating - Internal	1.30	Silver	7440-22-4	100.000	1.300	1000000	0.9618	9618
7	Die	3.32	Silicon	7440-21-3	99.800	3.317	998000	2.4542	24542
			Silicon Dioxide	60676-86-0	0.200	0.007	2000	0.0049	49
	Total Unit Weight =	135.17				135.17		100.0000	1000000